PCN Number:	20200805000.1	**PCN Date:**	Aug 6 2020
Title:	Qualification of PTI as a new assembly site for select Devices		
Customer Contact:	PCN Manager	**Dept:**	Quality Services
Proposed 1st Ship Date:	Nov 4 2020	**Estimated Sample Availability:**	Date provided at sample request

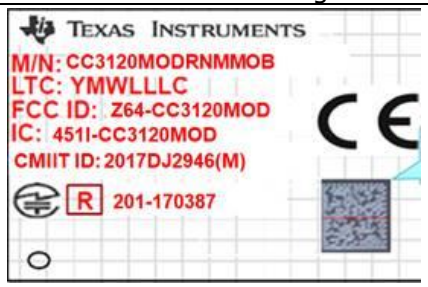
Change Type:

☒	Assembly Site	☐	Design	☐	Wafer Bump Site
☐	Assembly Process	☐	Data Sheet	☐	Wafer Bump Material
☐	Assembly Materials	☐	Part number change	☐	Wafer Bump Process
☐	Mechanical Specification	☐	Test Site	☐	Wafer Fab Site
☐	Packing/Shipping/Labeling	☐	Test Process	☐	Wafer Fab Materials
				☐	Wafer Fab Process

PCN Details

Description of Change:

Texas Instruments Incorporated is announcing the qualification of PTI as a new Assembly site for devices listed below in the product affected section. There are no construction differences between the current and new assembly sites, but there are device symbolization differences:

	FXC	PTI
Device marking differences	✓ 'SSSS' present ✓ 'XXXXXXXXXXXX-VVSS' Present ✓ CE logo bottom right ✓ BC label upper right	✓ 'SSSS' removed ✓ 'XXXXXXXXXXXX-VVSS' Removed ✓ CE logo mid right ✓ BC Label bottom right
Device Marking example Pic		

Reason for Change:

Supply continuity

Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):

None

Anticipated impact on Material Declaration

☒	No Impact to the Material Declaration	☐	Material Declarations or Product Content reports are driven from production data and will be available following the production release. Upon production release the revised reports can be obtained at the site link below http://www.ti.com/quality/docs/materialcontentsearch.tsp

Changes to product identification resulting from this PCN:

Assembly Site	Assembly Site Origin (22L)	Assembly Country Code (23L)	Assembly City
Foxconn	FXC	CHN	Chongqing
PTI	**PT2**	**TWN**	**HSINCHU CITY**

Sample product shipping label (not actual product label)

Product Affected:

CC3120MODRNMMOBR	CC3220MODASM2MONR	CC3220MODSF12MOBR	CC3220MODSM2MOBR
CC3220MODASF12MONR			

TEXAS INSTRUMENTS

TI Information
Selective Disclosure

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	Test Name / Condition	Duration	Package QBS Reference: CC3235MODSF12MOB	Product QBS Reference: CC3220MODASF12MON	Product QBS Reference: CC3220MODSF12MOB
TH	Unbiased Temperature and Humidity, 85C/85%RH	500 Hours	1/45/0	-	2/90/0
THB	Temperature and Humidity Bias, 85C/85%RH	1000 Hours	-	-	2/46/0
CDM	ESD CDM	500 V	1/3/0	-	2/6/0
HBM	ESD HBM	2000 V	1/3/0	-	2/6/0
HTOL	Life Test, 85C	1000 Hours	1/30/0	-	2/26/0
HTSL	High Temp. Storage Bake, 125C	1000 Hours	1/45/0	-	2/90/0
SD	Solderability	Solderability	1/5/0	-	2/10/0
TC	Temperature Cycle, -40/125C	400 Cycles	1/45/0	-	-
TC	Temperature Cycle, -40/105C	1000 Cycles	-	2/78/0	2/46/0

- QBS: Qualification By Similarity
- Qualification/QBS Devices CC3220MODASF12MON and CC3220MODSF12MOB are qualified at Moisture Sensitivity LEVEL3-250C. QBS Device CC3235MODSF12MOB is qualified at Moisture Sensitivity LEVEL3-260C.
- Preconditioning was performed for Unbiased Temperature and Humidity, Temperature Cycle, and High Temp. Storage Bake.
- Quality and Environmental data is available at TI's external Web site: http://www.ti.com/
- **Green/Pb-free Status:**
- Qualified Pb-Free(SMT) and Green

For questions regarding this notice, e-mails can be sent to the contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
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